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Earnings Conference for FY2027/3 2Q

2026/11/04

TOKYO SEIMITSU CO., LTD.

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- **Cautionary Statement with respect to Forward-Looking Statements :** This presentation data and information verbally provided contain "forward-looking statements" that are based on current best available information and policies. There are various factors such as world economic conditions and semiconductor/automobile market conditions which will directly and indirectly impact the Company's results in the future. As a result, future outcomes may differ from those projected in this presentation.
- **Wordings and Data in presentation :** Unless otherwise noted, "SPE" denotes our Semiconductor Production Equip. Segment, "Metrology (or Metr.)" denotes our Metrology Equip.Segment, "Net profit" denotes Net profit attributable to owner of the parent, and "MTP" denotes Mid-Term business Plan.
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Executive Summary

FY2027/3 1H/2Q Results	• **Company-wide sales, all profits, and orders each reached new fiscal-half and quarterly highs** • **Strong demand continues, particularly for SPE**
FY2027/3 Forecast	• **FY Forecasts raised (Sales: ¥189.0B => ¥192.0B; OP ¥44.0B => ¥45.0B)** • **Both sales and OP expected to meet MTP quantitative targets** • **Dividend projection updated following the Revision of forecasts (¥304 per share => ¥316 per share)**
Outlook for FY2028/3 and Beyond	• **Our equipment's market to continue expanding through at least CY2028** • **Aim to double our Prober production capacity by mid-FY2028** • **Continue to monitor component constraint risks closely**

- Hello everyone, I am Kimura, CEO of Tokyo Seimitsu. Thank you very much for your continued support.
- Let me explain the summary of today's presentation on page 2.
- Regarding our financial results for the first half (1H) and second quarter (2Q) of FY2027/3, company-wide sales, all profits, and orders each reached new highs for both the half-year and the quarter. We continued to see strong demand for SPE.
- We have revised our FY2027/3 business forecast from the forecast disclosed in August, setting both net sales and operating income forecasts at levels consistent with the quantitative targets of our MTP(Mid-term management plan). Simultaneously, We have also revised our dividend projection.
- Regarding the outlook for FY2028/3 and beyond, we predict that Our equipment's market will continue to grow at least through 2028, and we will proceed our initiatives aimed at doubling prober production volume.
- That concludes the summary. Koizumi will now explain our 1H and 2Q results.

FY2027/3 First Half (1H) Results

Orders, Sales, and all profits reached new half-year highs. Orders for SPE exceeded 100.0BJPY

Company-Wide results (BJPY)	FY2026/3 1H	FY2026/3 2H	FY2027/3 1H	HoH	YoY
Orders	80.6	82.5	**139.0**	+69%	+72%
Sales	77.1	89.8	**92.4**	+3%	+20%
Operating profit (OP)	14.7	19.0	**20.3**	+7%	+38%
(OP Margin) (OPM)	(19.1%)	(21.2%)	**(22.0%)**	+0.8pt	+2.9pt
Recurring profit	15.0	19.8	**21.1**	+7%	+41%
Net profit	9.6	15.1	**15.5**	+2%	+61%
R&D	5.5	6.5	**6.8**	+4%	+22%
Capex	6.9	4.2	**4.7**	+13%	-32%
Depreciation	2.7	2.9	**2.9**	+1%	+11%

Segment Results(BJPY)		FY2026/3 1H	FY2026/3 2H	FY2027/3 1H	HoH	YoY
SPE	Orders	61.3	62.1	**114.1**	+84%	+86%
	Sales	59.4	68.5	**72.6**	+6%	+22%
	OP	12.3	16.1	**17.7**	+10%	+44%
	(OPM)	(20.8%)	(23.5%)	**(24.4%)**	+0.9pt	+3.6pt
Metr.	Orders	19.3	20.4	**24.9**	+22%	+29%
	Sales	17.7	21.3	**19.8**	-7%	+12%
	OP	2.4	2.9	**2.6**	-11%	+10%
	(OPM)	(13.5%)	(13.8%)	**(13.3%)**	-0.5pt	-0.2pt

- Hello everyone, I am Koizumi, CFO. Thank you very much for your continued support. I will explain about FY2027/3 1H and 2Q results.
- Page 3 provides a summary of our consolidated financial results for the 1H FY2027/3.
- In the upper section, which covers company-wide results, orders, sales, and all profits reached new first-half highs. Orders exceeded ¥130.0B, and the OPM improved to 22.0%.
- In the lower section, results by segment, orders in the SPE segment increased by over 80% year over year (YoY), reaching the ¥100.0B range for the first time in a half-year period, while the OPM also reached the 24% range.
- In the Metrology equipment segment as well, orders reached a new peak, and both sales and OP were high for the first half of the past fiscal years.

FY2027/3 2Q Quarterly Results

2Q results set a new quarterly record. Sales exceeded the target by approx. ¥4.0B, and the OPM also improved

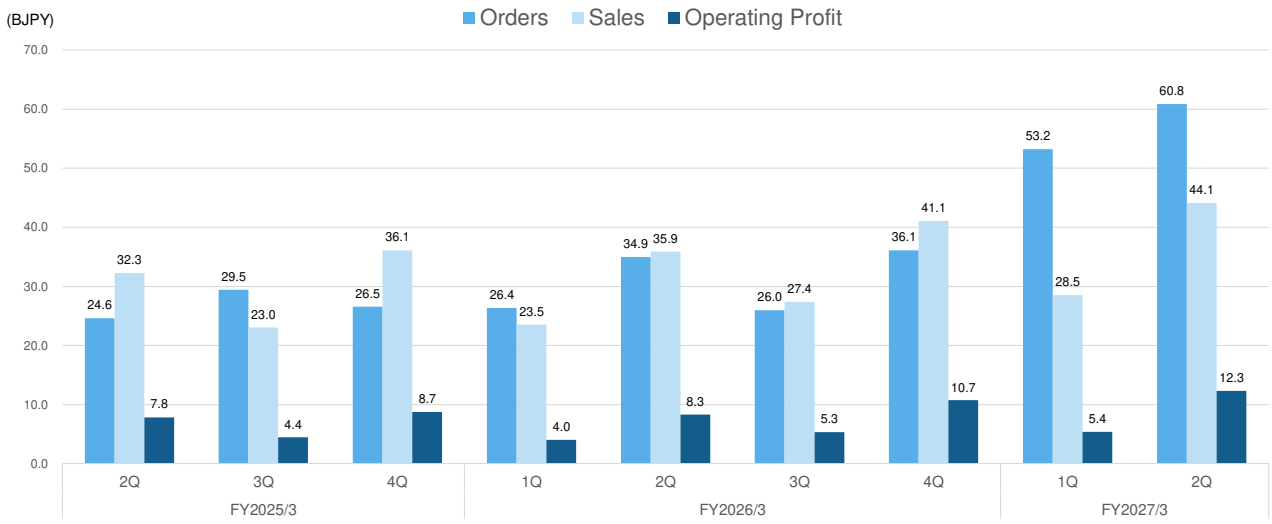
Company-Wide results (BJPY)	FY2026/3 1Q	2Q	3Q	4Q	FY2027/3 1Q	2Q	QoQ	YoY
Orders	35.9	44.7	36.6	45.8	65.8	73.1	+11%	+64%
Sales	30.9	46.2	35.9	53.9	36.7	55.7	+52%	+21%
Operating profit (OP)	4.6	10.1	6.2	12.8	5.9	14.4	+144%	+42%
(OP Margin) (OPM)	(14.8%)	(21.9%)	(17.3%)	(23.8%)	(16.1%)	(25.9%)	+9.8pt	+4.0pt
Recurring profit	4.5	10.5	6.7	13.1	6.4	14.7	+129%	+40%
Net profit	3.2	6.4	4.5	10.6	4.7	10.8	+132%	+70%
R&D	2.5	3.0	2.9	3.6	3.3	3.4	+3%	+13%
Capex	2.5	4.4	1.5	2.7	1.9	2.8	+43%	-37%
Depreciation	1.2	1.4	1.4	1.6	1.4	1.5	+5%	+5%

Segment Results		1Q	2Q	3Q	4Q	1Q	2Q	QoQ	YoY
SPE	Orders	26.4	34.9	26.0	36.1	53.2	60.8	+14%	+74%
	Sales	23.5	35.9	27.4	41.1	28.5	44.1	+55%	+23%
	OP	4.0	8.3	5.3	10.7	5.4	12.3	+128%	+48%
	(OPM)	(17.1%)	(23.1%)	(19.5%)	(26.1%)	(19.0%)	(27.9%)	+8.9pt	+4.8pt
Metr.	Orders	9.5	9.8	10.7	9.7	12.6	12.3	-2%	+26%
	Sales	7.3	10.3	8.5	12.8	8.2	11.6	+41%	+12%
	OP	0.5	1.8	0.9	2.1	0.5	2.1	+313%	+15%
	(OPM)	(7.5%)	(17.8%)	(10.2%)	(16.3%)	(6.2%)	(18.3%)	+12.0pt	+0.5pt

- Page 4 shows our quarterly results. I summarize our 2Q results.
- 2Q company-wide results also reached a new peak. Orders totaled ¥73.1B, surpassing even the high level recorded in the 1Q.
- In the second column, Sales totaled ¥55.7B, which was approximately ¥4.0B above our target. While the original plan for the 2Q was to increase sales compared to the 1Q, not only did production, shipments, and installations proceed largely as planned, but there were also some sales that were brought forward.
- The bottom section shows results by segment. Both segments saw increases in both sales and OP YoY; in the SPE segment, the OPM reached a high level of approximately 28%, while in the Metrology segment, it stood at 18%.

SPE Segment Quarterly Trend

2Q orders were above expectations, driven by continuing HPC business as well as strong demand from China, etc.

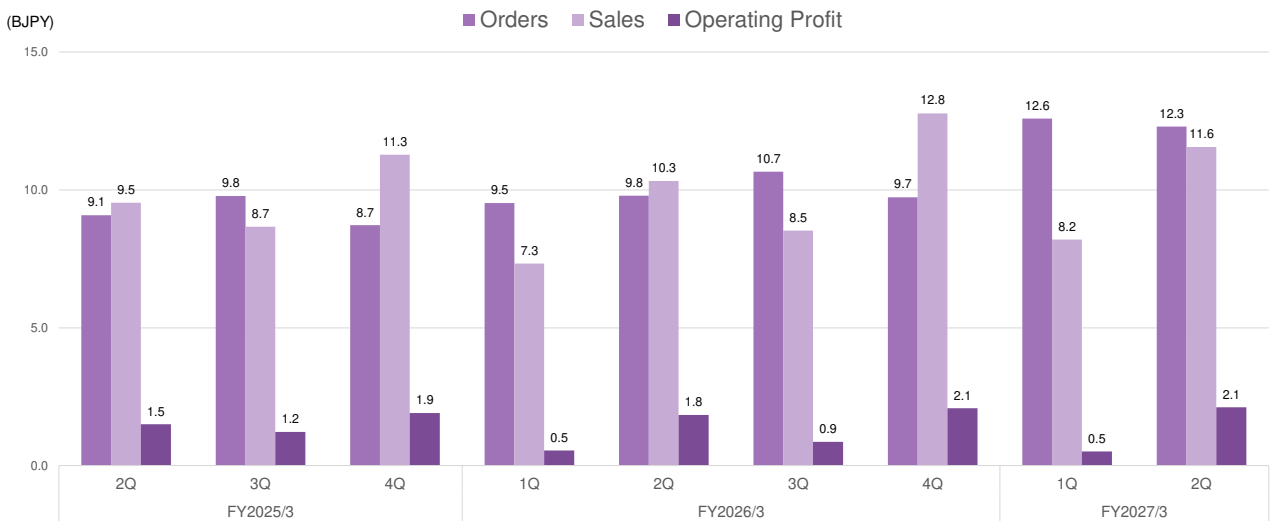


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- Page 5 shows the quarterly trends in SPE orders, sales, and OP.
- On the right, for the 2Q FY2027/3. orders (shown in light blue) totaled ¥60.8B, which was nearly ¥20.0B higher than the company's forecast. In addition to ongoing projects for HPC and many projects in China, inquiries for conventional memory and logic chips were strong, and some opportunities that are originally anticipated for the 2H FY2027/3 were brought forward.
- Note that the Company examines outstanding backlog visibility quarterly. And those for having lower visibility of realizing revenue are liquidated. In 2Q, due to that, orders and backlogs decreased by slightly above than ¥1.0B.
- Detailed quantitative information is included in the supplementary materials on the disclosure documents; please refer to those as well.

Metrology Segment Quarterly Trend

2Q orders at a high level thanks to additional investments for HV production, AI data centers, robots, and others

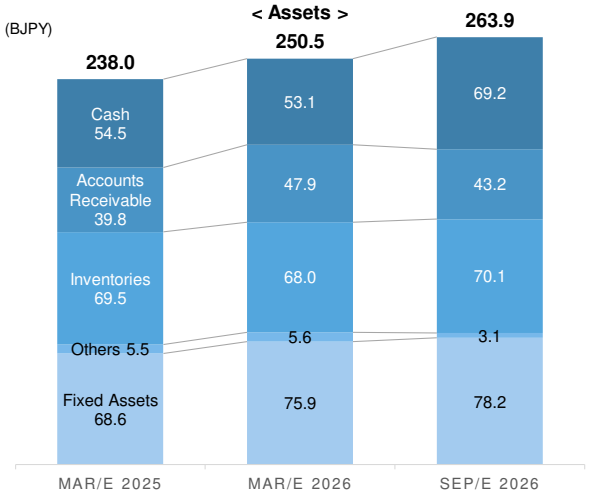


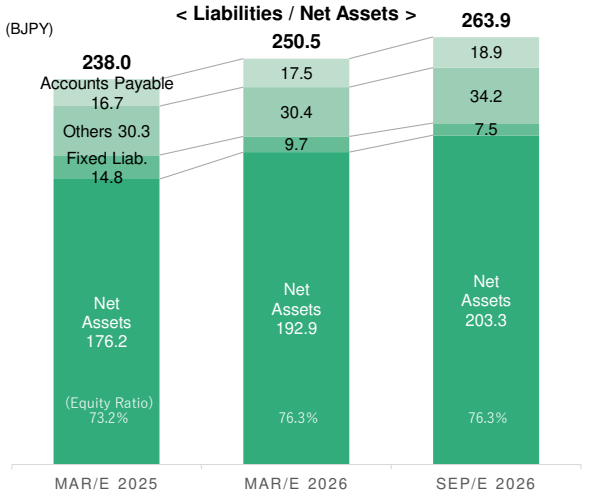
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- Page 6 shows the quarterly trends in Metrology segment orders, sales, and OP.
- 2Q orders totaled ¥12.3B, which was also more than ¥2.0B above the expectations.
- Although we had anticipated a seasonal order decline, due to the expansion of the manufacturing market, as well as strong demand for AI data centers robots-related products, orders remained flat QoQ.

Balance Sheet

Cash and cash equivalents, inventories, and fixed assets increased compared to Mar/E



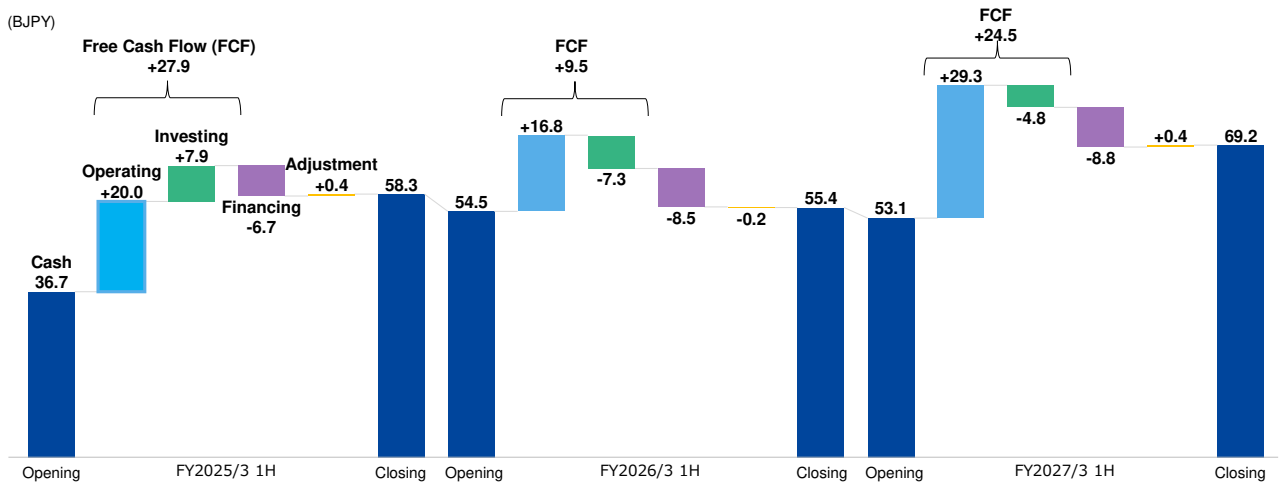


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- Page 7 explains the balance sheet.
- Total assets as of the end of September 2026 amounted to ¥263.9B, an increase of ¥13.0B from the end of March.
- On the assets section cash and cash equivalents increased due to the collection of accounts receivable, and inventory also increased in anticipation of future growth in shipments.
- On the right side, under Liabilities, accounts payable increased, and under Net assets, retained earnings increased simultaneously.
- The equity ratio as of the end of September was 76.3%, remained flattish from the end of March .

Cash Flows

Resulted positive free cash flow owing to profit

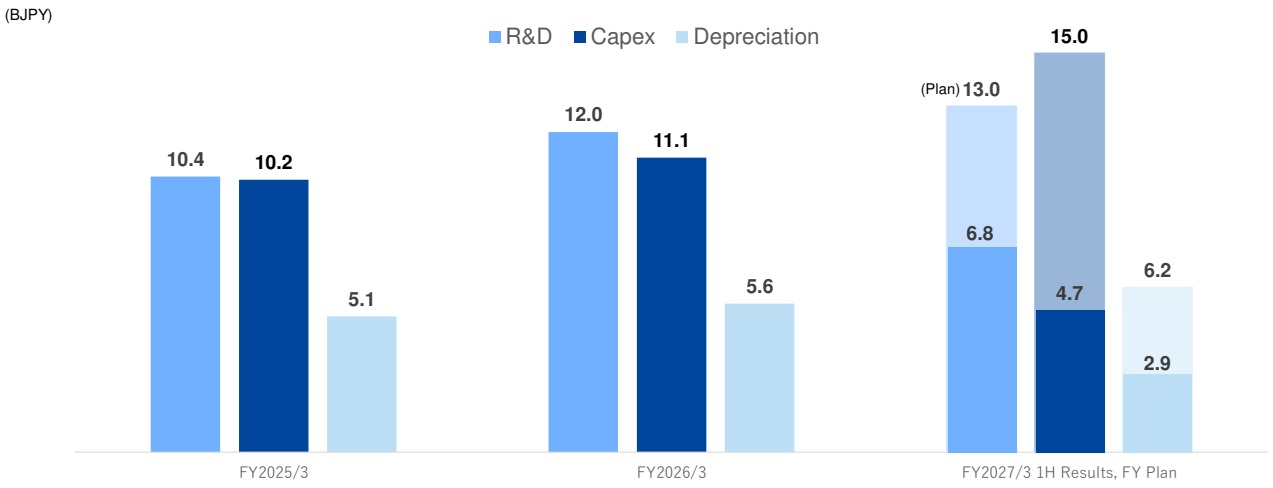


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- Page 8 explains cash flow. These are 1H results for these 3 fiscal years.
- Cash flow from operating activities was +¥29.3B mainly owing to profit, while cash flow from investing activities was -¥4.8B due to the purchase of fixed assets. Free cash flow came to +¥24.5B.
- Cash flow from financing activities was - ¥8.8B, primarily due to dividend payments. As a result, cash and cash equivalent at the end of the 1H FY2027/3 was ¥69.2B.

R&D, Capex and Depreciation

FY Plan for FY2027/3 remains unchanged



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- Page 9 shows the actual and planned figures for R&D, Capex, and depreciation.
- The results for the 1H FY2027/3 are as shown.
- Capex planned for FY2027/3 include investments in a new manufacturing plant and demonstration centers. Most of these are scheduled for the 2H FY2027/3.
- There are no changes to the FY plan from what we explained in August.
- My explanation about 1H and 2Q results is all for now. Next, CEO Kimura will explain business outlook for FY2027/3 and other related matters.

Premises of FY2027/3 Forecast (Blue: changed by November)

Sales & Profits

SPE： Revised FY forecast after considering 1H results, production trends, and component procurement

- HPC-related including Gen.AI： Sales/profits contribution to rise
- Global OSAT：Growth is seen not only in HPC but also in conventional logic devices
- China Demands：Maintain firm demand driven by high-end use
- Memory (Non-HBM)：Shipments for DRAM/NAND to increase

Metr.： Increase YoY amid recover in industry, price revision, and businesses among aerospace, defense and semis
Profits：Although pressures from an increase of various costs including from a manufacturing volume increase remain, meeting OP target set in the MTP is now expected

Order Trend

SPE： Order trends to remain very strong in 2H FY2027/3 expect FY orders to total approx. ¥220.0B (YoY +80%)

- HPC-related including Gen.AI : Expect very strong trend to continue
- Global OSAT： Demand related to conventional logic devices related will keep strong tone
- China Demands： Solid demand remains mainly for high-end use
- Memory (Non-HBM)： Expect acceleration toward DRAM/NAND investments

Metr.：Expect increasing opportunities among in aerospace, defense, AI infrastructures, semis, and from subsidy-related business

- This is Kimura. I will now explain our FY2027/3 FY outlook.
- Page 10 shows the premises for our FY outlook, which we presented in August, with updates highlighted in blue.
- First, regarding our outlook for sales and profits, we have revised our full-year sales forecast after comprehensively considering 1H, current production levels, and trends in component procurement. The forecast for the 2H remains largely unchanged from the August projection; the FY revision is primarily due to the better-than-expected performance in the 1H.
- Consequently, we have also revised our FY OP forecast. We now expect to achieve the quantitative targets of our MTP one year ahead of schedule.
- In the lower section shows order trend. Particularly in the SPE segment, we expect the strong order environment to continue in the 2H to be almost similar level with the first half. If this materializes, we project FY SPE order to reach approx. ¥220.0B, up 80% YoY.

FY2027/3 Forecast

The forecast disclosed on Aug 4th, 2026, has been revised (upward revision for SPE)
Forex assumption remains unchanged : ¥150 / US$ (Forex impact is minimal: High ratio of Yen-based businesses)
Per share dividend projection has also been updated following forecast revision

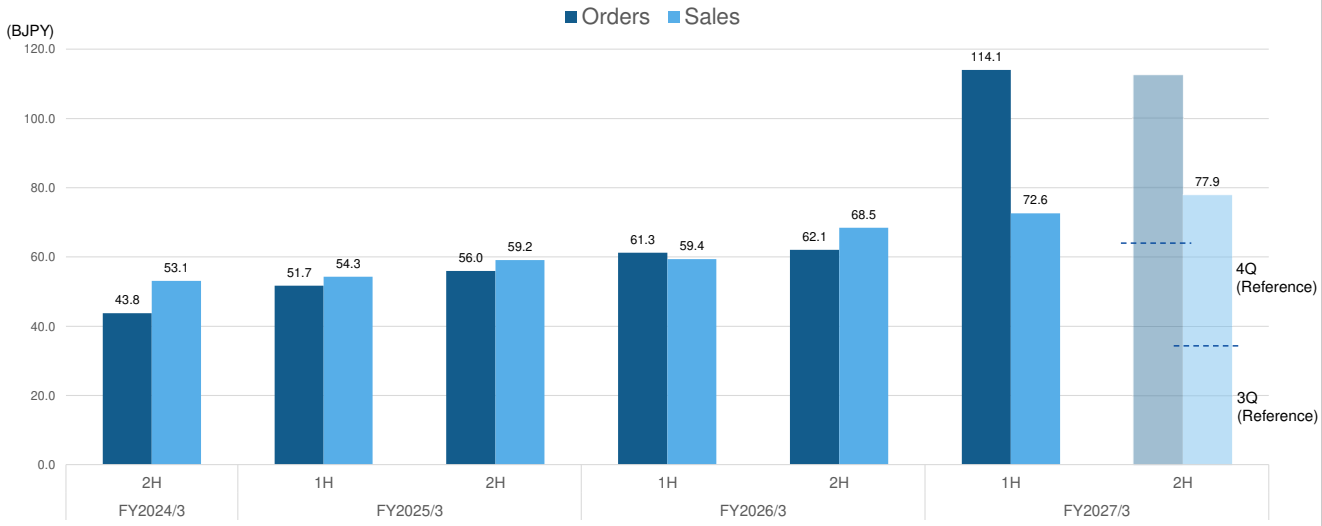
Company-Wide results (BJPY)	FY2026/3 1H	2H	Full Year	FY2027/3 1H	2H(f)	Full Year	Changes	YoY
Orders	80.6	82.5	163.1	139.0	-	-	-	-
Sales	77.1	89.8	166.8	92.4	**99.6**	**192.0**	+3.0	+15%
Operating profit	14.7	19.0	33.7	20.3	**24.7**	**45.0**	+1.0	+33%
(OP Margin)	(19.1%)	(21.2%)	(20.2%)	(22.0%)	**(24.8%)**	**(23.4%)**	+0.2pt	+3.2pt
Recurring profit	15.0	19.9	34.8	21.1	**24.4**	**45.5**	+1.5	+31%
Net profit	9.6	15.1	24.7	15.5	**16.5**	**32.0**	+1.2	+29%
R&D	5.5	6.5	12.0	6.8	**6.2**	**13.0**	±0.0	+8%
Capex	6.9	4.2	11.1	4.7	**10.3**	**15.0**	±0.0	+36%
Depreciation	2.7	2.9	5.6	2.9	**3.3**	**6.2**	±0.0	+11%

Segment Sales	FY2026/3 1H	2H	Full Year	FY2027/3 1H	2H(f)	Full Year	Changes	YoY
SPE	59.4	68.5	127.9	72.6	**77.9**	**150.5**	+3.0	+18%
Metr.	17.7	21.3	39.0	19.8	**21.7**	**41.5**	±0.0	+7%
Dividend per share (JPY)	111	151	262	158	**158**	**316**	+12	+54

- Based on that, we have revised our full-year forecast for FY2027/3, which we previously disclosed on August 4th, as shown in page 11.
- Specifically, driven primarily by better-than-expected results in the 1H, we have revised our SPE sales forecast upward by ¥3.0B and our OP forecast upward by ¥1.0B. Since the OP target in our MTP was ¥45.0B, we were able to set the forecast at this level.
- Although there are concerns about rising material cost and opex, we expect the OPM to improve by approximately 3pt YoY. We forecast a company-wide OPM margin of 23.4%, and plan for the SPE segment to achieve an OPM in the 25% range.
- In line with the revision to OP, we have also revised our forecasts for recurring profit and net profit.
- As a result, we have revised our FY per share dividend projection, to ¥316 per share, an increase of ¥54 YoY. Please also refer to our timely disclosure regarding this change.
- The assumed exchange rate is remaining unchanged as ¥150 per US dollar.

SPE Sales/Orders incl. Forecasts

Anticipate that order levels for the 2H FY2027/3 will remain high (on the same level with the 1H)



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- Page 12 shows forecasts of SPE's sales and orders per fiscal half.
- As I mentioned earlier, we expect orders in the 2H FY2027/3 on the same level with the 1H. We anticipate that strong demand will continue not only for HPC but also for conventional memory and logic devices.
- We have mentioned previously that we expect to receive orders for hybrid bonding grinders in the 2H this fiscal year. At this time, based on discussions with customers, we have factored the recognition of orders for units currently being shipped as evaluation units into our forecast.
- Outlook of product composition ratio for FY2027/3 2H is; In sales, High-60% for Probers, and Low-30% for Assembly machines. In orders, Low-70% for Probers, and High-20% for Assembly machines. Of note, the estimated breakdown by quarter is as shown in the materials.

Metrology Sales/Orders incl. Forecasts

Estimate 2H orders to decline HoH owing to typical seasonal patterns (FY order likely to increase by 10% YoY)



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- Page 13 shows forecasts of Metrology's sales and orders per fiscal half.
- The Metrology segment continues to operate in a robust business environment, but the order plan for the 2H factors in a seasonal decline. Even so, FY orders are expected to increase by 10% YoY.
- Outlook of product composition ratio for FY2027/3 1H is ; In sales, Low-60% for Measuring Instruments, High-20% for Automatic Gauges, remainder for Battery Testing systems. In orders, Mid-60% for Measuring Instruments, 30% for Automatic Gauges, remainder for Battery Testing systems.

Outlook for FY2028/3 and beyond

SPE

- The expansion of the Company's TAM will continue until at least CY2028 (Assume +20% CAGR for the probers market)
- Aim to double our prober manufacturing capacity by mid-FY2029/3 compared to the 1H FY2027/3 through:
  - + low-30% in FY2027/3 ; upon expansion of production space at the *Hanno* Plant (Phase 1) (previous estimate: 20%)
  - + mid-20% in FY2028/3 ; upon expansion of production space at the *Hanno* Plant (Phase 2)
  - + mid-20% in FY2029/3 ; upon completion of the *Hanno* No.2 Plant construction (Phase 1)
- Meanwhile, risks related to component procurement require close monitoring

Metrology

- On top of additional investments related to HV production, demand will grow in the aerospace and defense sectors.
- Sectors related to AI data centers (including infrastructure) and robotics for automation and labor-saving initiatives will continue to perform well
- The manufacturing market, driven primarily by outside-of-Japan demand, will continues expand

Mid-term Business Plan(MTP)

- Aim to launch a new MTP starting in FY2028/3, if the Company will achieve our current MTP target during FY2027/3
- The Company currently reviews period, quantitative targets, and others

- Page 14 outlines our outlook for FY2028/3 and beyond.
- In the top section, regarding SPE, we predict that the expansion of our total available market (TAM) for our product will continue at least through CY2028. For our probers, based on a comprehensive assessment of customer feedback and other factors, we anticipate +20% CAGR.
- Expanding prober production capacity is a key challenge. We once verbally explained our expansion plans at the August briefing, but since then we have continued to explore various measures and are proceeding actions to double prober production volume—compared to 1H FY2027/3—by the middle of FY2029/3. Specifically, as you can see, we plan to increase production in stages through the middle of FY2029/3.
- Meanwhile, risks related to component procurement persist. We will formulate future earnings forecasts taking these procurement trends into account.
- Regarding Metrology segment, the business environment appears likely to support stable growth.
- Regarding the lower section, if we achieve the quantitative targets of our current MTP within FY2027/3, we intend to launch a new MTP starting from FY2028/3. We are currently reviewing the timeframe, quantitative targets, and others, and will provide updates as appropriate.
- That concludes my presentation. Thank you for your attention.

質疑応答 / Q&A

Supplementary Data - 生成AIを含むHPC / HPC-related business incl. Gen.AI

<売上高/Sales>

(前半期比増減率 / HoH Changes)	2025年度下期 FY2026/3 2H	2026年度上期 FY2027/3 1H	2026年度下期予 FY2027/3 2H (f)
生成AIを含むHPC 全体 HPC-related incl. Gen. AI	前半期比 +32% HoH	前半期比 +48% HoH	前半期比 -5% HoH
うちロジック (生成AIを含む) of which Logic (incl. Gen AI)	前半期比 +11% HoH	前半期比 +105% HoH	前半期比 -3% HoH
うちHBM of which HBM	前半期比 +64% HoH	前半期比 -8% HoH	前半期比 -12% HoH
SPE売上高に占めるHPC関連の割合 HPC-related proportion of total SPE sales	30%半ば / Mid-30%	50%	40%半ば / Mid 40%

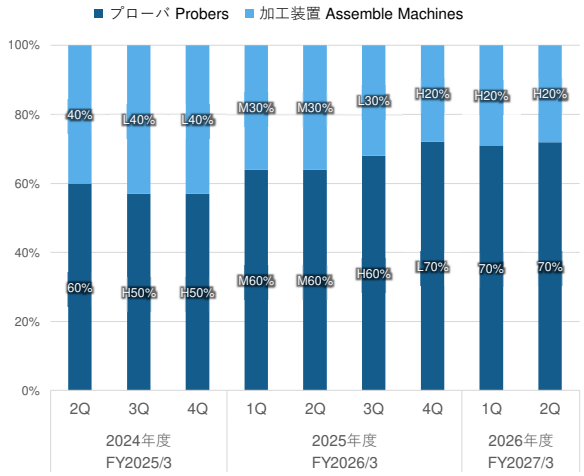
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(前半期比増減率 / HoH Changes)	2025年度下期 FY2026/3 2H	2026年度上期 FY2027/3 1H	2026年度下期予 FY2027/3 2H (f)
生成AIを含むHPC 全体 HPC-related incl. Gen. AI	前半期比 +4% HoH	前半期比 +90% HoH	前半期比 +6% HoH
うちロジック (生成AIを含む) (*) of which Logic (incl. Gen AI) (*)	前半期比 +84% HoH	前半期比 +83% HoH	前半期比 +3% HoH
うちHBM of which HBM	前半期比 -48% HoH	前半期比 +105% HoH	前半期比 +12% HoH
SPE受注高に占めるHPC関連の割合 HPC-related proportion of total SPE orders	40%	40%	40%半ば / Mid 40%

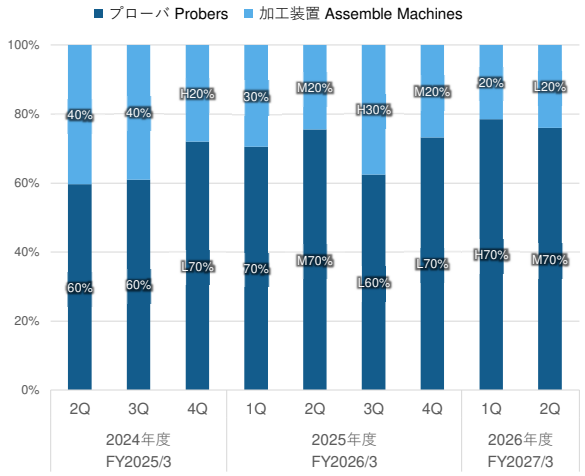
- 変動が大きいため、四半期別の開示は行っておりません。 Due to significant volatilities, the Company does not provide quarterly forecasts.
- 『生成AIを含むHPC全体』は、「うちロジック(生成AIを含む)」および「うちHBM」の合計です。「うちロジック(生成AIを含む)」には、ロジックデバイス向けプローバやAIパッケージング向けの加工装置の需要が含まれています。なお、当社は製品の特性上、検査や加工がおこなわれる半導体デバイスの種別を特定することが困難であることから、生成AIに限定した分類は行っておりません。"HPC-related incl. Gen.AI" represents the sum of 'of which Logic (incl. Gen.AI)' and 'of which HBM'. The 'of which Logic (incl. Gen. AI)' encompasses businesses for probers for logic devices and assembly equipment for AI packaging. Note that due to the nature of our products, it is difficult to identify the specific types of semiconductor devices undergoing inspection or processing; consequently, the Company does not undertake classification limited solely to Generative AI.

Supplementary Data - 製品別構成比 半導体 / SPE Segment per Product

<売上高　Sales>



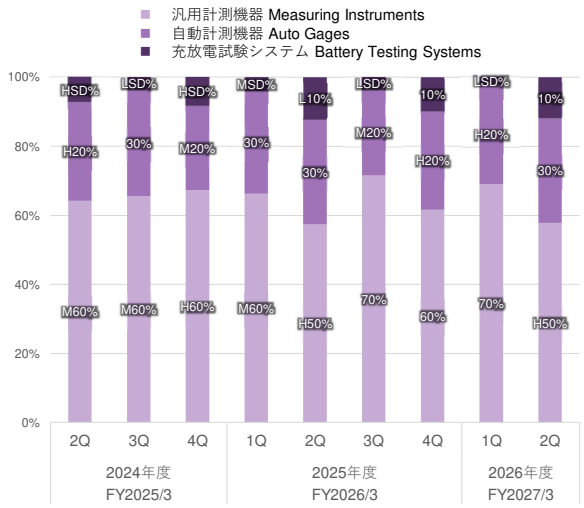
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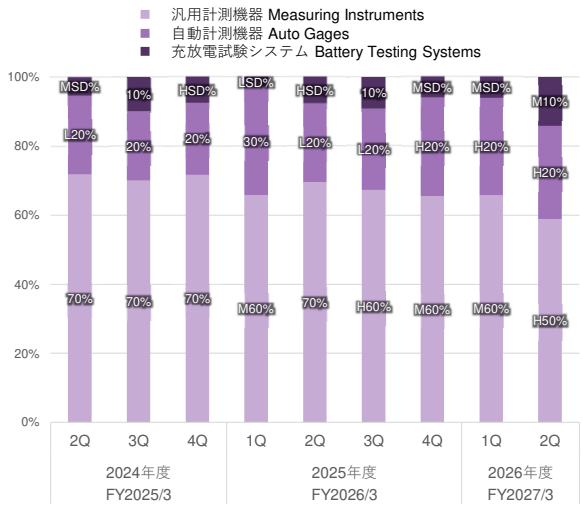
備考：表中の記載は、L:Low(前半), M:Middle(半ば), H:High(後半)を、LSD%：一桁%前半 (0-3%) 、MSD% :一桁%半ば (4-6%)、HSD%:一桁%後半 (7-9%)を示します。内訳の合計が100%にならない場合があります。
Note: The entries in the table represent L: Low, M: Middle, and H: High; LSD%: Low Single Digit % (0-3%), MSD%: Mid Single Digit % (4–6%), and HSD%: High Single Digit % (7–9%), respectively. SUM may not equal 100%.

Supplementary Data - 製品別構成比 計測 / Metrology Segment per Product

<売上高　Sales>



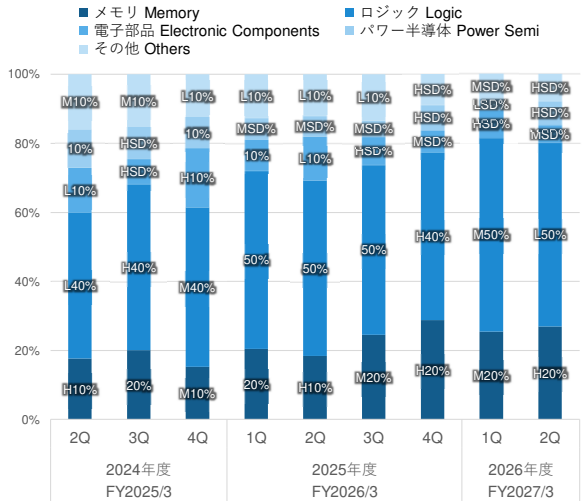
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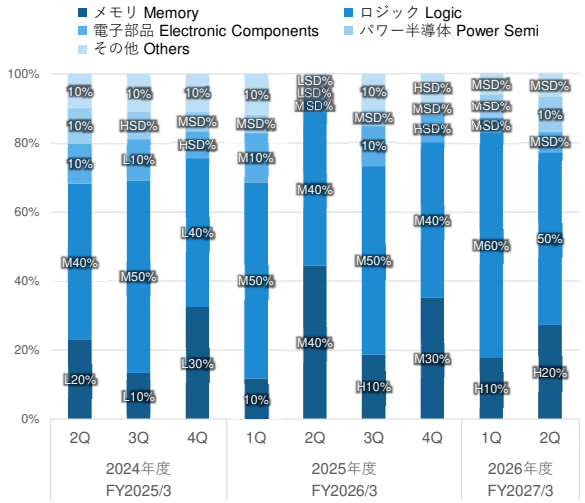
備考：表中の記載は、L:Low(前半), M:Middle(半ば), H:High(後半)を、LSD%：一桁%前半 (0-3%) 、MSD% :一桁%半ば (4-6%)、HSD%:一桁%後半 (7-9%)を示します。内訳の合計が100%にならない場合があります。
Note: The entries in the table represent L: Low, M: Middle, and H: High; LSD%: Low Single Digit % (0-3%), MSD%: Mid Single Digit % (4–6%), and HSD%: High Single Digit % (7–9%), respectively. SUM may not equal 100%.

Supplementary Data - アプリ別構成比 半導体 / SPE Segment per Application

<売上高　Sales>



<受注高　Orders>

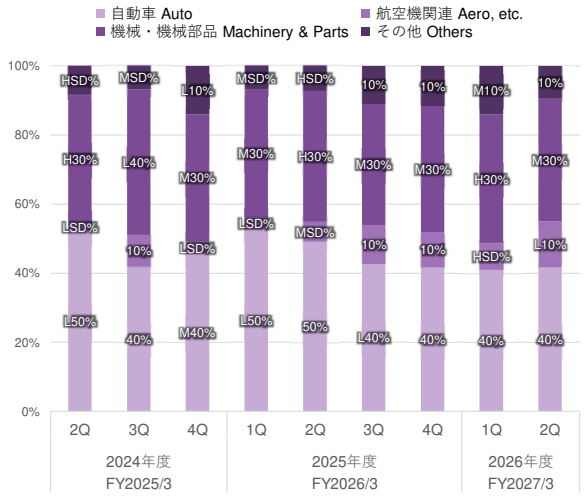


備考：表中の記載は、L:Low(前半), M:Middle(半ば), H:High(後半)を、LSD% : 一桁%前半 (0-3%) 、MSD% :一桁%半ば (4-6%)、HSD%:一桁%後半 (7-9%)を示します。内訳の合計が100%にならない場合があります。
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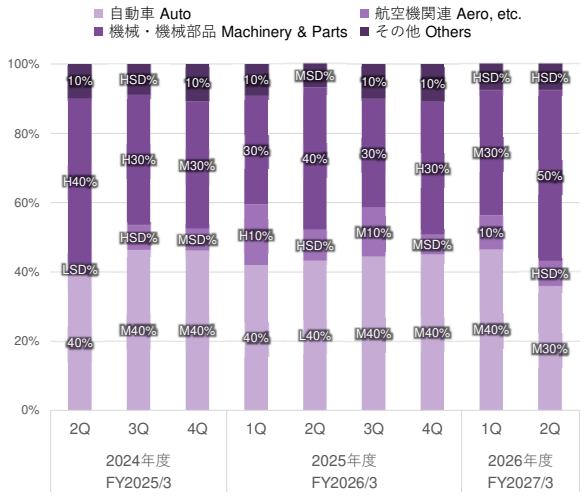
注) 2026年8月4日に開示した構成比データ(売上高、左側)に誤りがありましたので訂正しております。
Note: We have corrected the composition data (sales, left side) disclosed on August 4, 2026, as it contained an error.

Supplementary Data - アプリ別構成比 計測 / Metrology Segment per Application

<売上高　Sales>



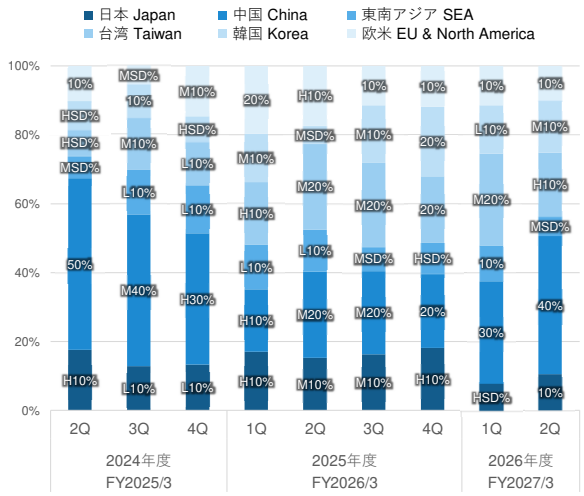
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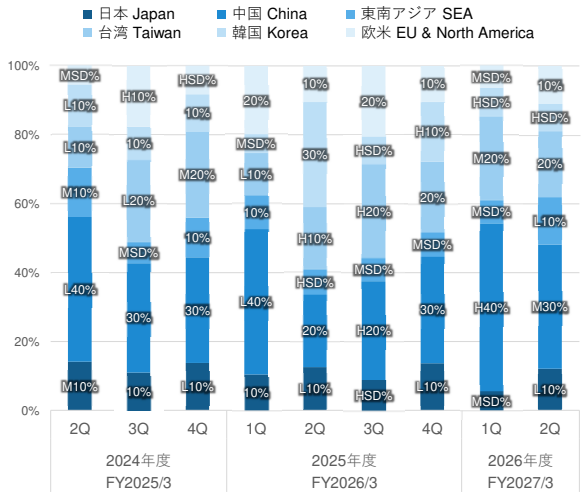
備考：表中の記載は、L:Low(前半), M:Middle(半ば), H:High(後半)を、LSD%：一桁%前半 (0-3%) 、MSD% :一桁%半ば (4-6%)、HSD%:一桁%後半 (7-9%)を示します。内訳の合計が100%にならない場合があります。
Note: The entries in the table represent L: Low, M: Middle, and H: High; LSD%: Low Single Digit % (0-3%), MSD%: Mid Single Digit % (4–6%), and HSD%: High Single Digit % (7–9%), respectively. SUM may not equal 100%.

Supplementary Data - 地域別構成比 半導体 / SPE per Region

<売上高　Sales>



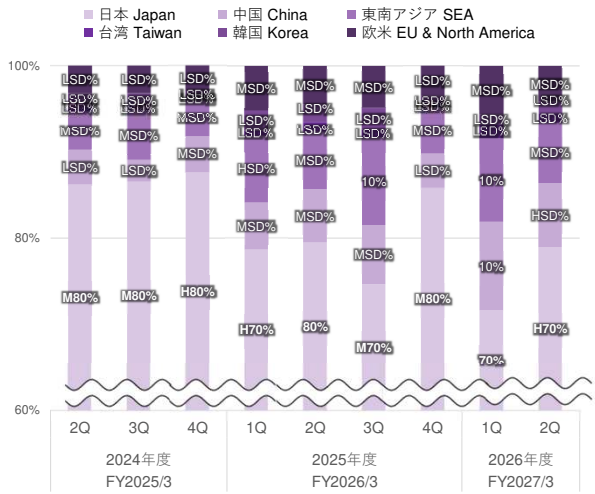
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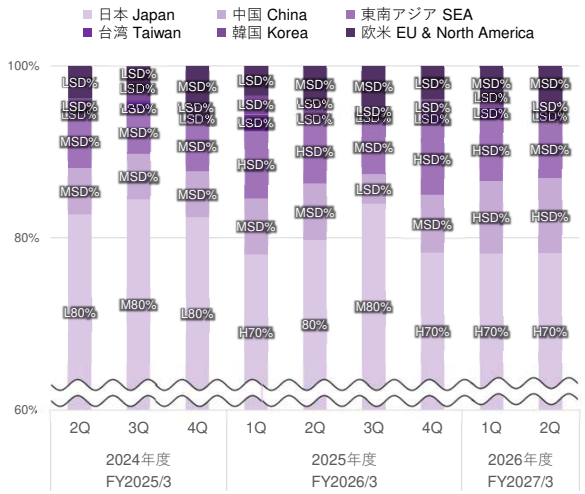
備考：表中の記載は、L:Low(前半), M:Middle(半ば), H:High(後半)を、LSD% : 一桁%前半 (0-3%) 、MSD% :一桁%半ば (4-6%)、HSD%:一桁%後半 (7-9%)を示します。内訳の合計が100%にならない場合があります。
Note: The entries in the table represent L: Low, M: Middle, and H: High; LSD%: Low Single Digit % (0-3%), MSD%: Mid Single Digit % (4–6%), and HSD%: High Single Digit % (7–9%), respectively. SUM may not equal 100%.

Supplementary Data - 地域別構成比 計測 / Metrology per Region

<売上高　Sales>



<受注高　Orders>



備考：取引顧客の国籍による分類であり、日本向け売上高・受注高には第3国への輸出案件が含まれています。This data classifies based on customers' nationality. Sales and orders for Japan include export transactions to third countries.

備考：表中の記載は、L:Low(前半), M:Middle(半ば), H:High(後半)を、LSD%：一桁%前半 (0-3%) 、MSD% :一桁%半ば (4-6%)、HSD%:一桁%後半 (7-9%)を示します。内訳の合計が100%にならない場合があります。
Note: The entries in the table represent L: Low, M: Middle, and H: High; LSD%: Low Single Digit % (0-3%), MSD%: Mid Single Digit % (4–6%), and HSD%: High Single Digit % (7–9%), respectively. SUM may not equal 100%.

Supplementary Data - セグメント別業績推移 / Segment

(百万円) Million Yen		連結会計期間 Consolidated Fiscal Year				四半期 Quarterly							
		2023年3月期 FY2023/3	2024年3月期 FY2024/3	2025年3月期 FY2025/3	2026年3月期 FY2026/3	2026年3月期 FY2026/3				2027年3月期 FY2027/3			
						1Q	2Q	3Q	4Q	1Q	2Q	3Q	4Q
受注高 Orders	半導体 SPE	99,366	86,082	107,713	123,396	26,378	34,945	25,965	36,106	53,236	60,837		
	計測 Metr.	36,960	34,802	37,917	39,700	9,523	9,786	10,661	9,728	12,583	12,302		
	合計 Total	136,326	120,885	145,631	163,096	35,901	44,732	36,627	45,835	65,820	73,140		
受注残高 Backlog	半導体 SPE	89,371	75,398	69,630	65,149	72,466	71,541	70,134	65,149	89,870	106,577		
	計測 Metr.	12,428	12,606	13,470	14,210	15,660	15,123	17,257	14,210	18,592	19,343		
	合計 Total	101,799	88,004	83,101	79,359	88,127	86,664	87,391	79,359	108,463	125,921		
売上高 Sales	半導体 SPE	112,365	100,055	113,481	127,878	23,542	35,870	27,372	41,092	28,515	44,130		
	計測 Metr.	34,436	34,624	37,053	38,960	7,333	10,323	8,528	12,775	8,201	11,552		
	合計 Total	146,801	134,680	150,534	166,839	30,876	46,194	35,900	53,867	36,716	55,682		
営業利益 OP	半導体 SPE	29,866	19,899	24,311	28,404	4,031	8,297	5,347	10,727	5,409	12,308		
	計測 Metr.	4,628	5,408	5,392	5,333	549	1,838	867	2,077	511	2,112		
	合計 Total	34,494	25,307	29,703	33,738	4,581	10,136	6,214	12,805	5,920	14,420		
営業利益率 OP Margin	半導体 SPE	26.6%	19.9%	21.4%	22.2%	17.1%	23.1%	19.5%	26.1%	19.0%	27.9%		
	計測 Metr.	13.4%	15.6%	14.6%	13.7%	7.5%	17.8%	10.2%	16.3%	6.2%	18.3%		
	合計 Total	23.5%	18.8%	19.7%	20.2%	14.8%	21.9%	17.3%	23.8%	16.1%	25.9%		

Supplementary Data - 損益計算書 / Income Statement

(百万円 (EPS除く)) Million Yen(excl. EPS)	連結会計期間 Consolidated Fiscal Year				四半期 Quarterly							
	2023年3月期 FY2023/3	2024年3月期 FY2024/3	2025年3月期 FY2025/3	2026年3月期 FY2026/3	2026年3月期 FY2026/3				2027年3月期 FY2027/3			
					1Q	2Q	3Q	4Q	1Q	2Q	3Q	4Q
売上高 Net Sales	146,801	134,680	150,534	166,839	30,876	46,194	35,900	53,867	36,716	55,682		
売上原価 Cost of goods sold	84,967	79,917	88,081	97,978	18,468	27,411	21,063	31,034	21,316	31,579		
売上総利益 Gross Profit on Sales	61,834	54,762	62,453	68,860	12,407	18,783	14,837	22,832	15,400	24,102		
販売費および一般管理費 Selling, general and administrative expenses	27,339	29,454	32,750	35,122	7,825	8,647	8,622	10,026	9,479	9,681		
営業利益 Operating profit	34,494	25,307	29,703	33,738	4,581	10,136	6,214	12,805	5,920	14,420		
営業外収益 Non-operating income	965	1,404	921	1,481	133	309	609	428	576	385		
営業外費用 Non-operating expenses	162	259	684	394	252	-69	84	126	66	90		
経常利益 Recurring Profit	35,297	26,453	29,939	34,825	4,462	10,515	6,739	13,108	6,430	14,715		
特別利益 Extraordinary gains	103	824	4,493	194	3	85	105	0	3	126		
特別損失 Extraordinary losses	2,099	21	158	1,833	-	2,103	-	-269	-	-		
税金等調整前当期/四半期純利益 Profit before income taxes and minority interests	33,301	27,255	34,275	33,186	4,465	8,498	6,844	13,377	6,434	16,540		
法人税等合計 Total Income tax and others	9,607	7,791	8,531	8,354	1,228	2,090	2,268	2,768	1,698	4,006		
非支配株主に帰属する当期/四半期純利益 Net Profit attributable to minority interests	62	84	106	92	7	25	39	18	67	13		
親会社株主に帰属する当期/四半期純利益 Net Profit attributable to Owners of the Parent	23,630	19,378	25,637	24,739	3,229	6,382	4,536	10,590	4,667	10,821		
1株当たり当期/四半期純利益(円) Net Profit per Share(Yen)	581.33	480.49	633.75	610.02	79.77	157.32	112.74	260.73	115.01	266.61		
潜在株式調整後 1株当たり当期/四半期純利益(円) Net Profit per Share(diluted)(Yen)	575.62	475.42	628.31	606.14	-	-	-	-	-	-		

Supplementary Data - 貸借対照表 / Balance Sheet

(百万円)(Million Yen)		2024年3月期 FY2024/3	2025年3月期 FY2025/3	2026年3月期 FY2026/3	2027年3月期 中間期 FY2027/3 Interim
流動資産 Current Assets	現金及び預金 Cash and cash equivalents	36,782	54,541	53,073	69,219
	売上債権※1 Accounts Receivable※1	42,801	39,809	47,877	43,229
	棚卸資産 Inventories	67,225	69,513	68,022	70,125
	その他 Others	7,022	5,477	5,634	3,106
	合計 Total	153,831	169,341	174,607	185,680
固定資産合計 Total Fixed Assets		71,693	68,610	75,925	78,228
総資産 Total Assets		225,524	237,952	250,533	263,909
流動負債 Current Liabilities	買入債務※2 Accounts Payable※2	17,845	16,665	17,529	18,898
	その他 Others	28,156	30,268	30,350	34,245
	合計 Total	46,002	46,933	47,879	53,144
固定負債合計 Total long-term liabilities		21,094	14,789	9,737	7,478
負債合計 Total Liabilities		67,097	61,723	57,617	60,623
純資産合計 Total Net Assets		158,427	176,229	192,916	203,285
負債・純資産合計 Total Liabilities and Net Assets		225,524	237,952	250,533	263,909
有利子負債合計 Total interest-bearing debt		25,171	20,084	14,713	12,190
自己資本比率 Equity Ratio(%)		69.4%	73.2%	76.3%	76.3%
自己資本利益率 ROE(%)		12.9%	15.5%	13.5%	13.6%

※1: 電子記録債権、契約資産を含みます。 Incl. Electronically recorded monetary claims.
※2: 電子記録債務を含みます。 Incl. Electronically recorded obligations-operating.

Supplementary Data - 各種費用, キャッシュフロー/ Expenses and

(百万円)(Million Yen)	2024年3月期 FY2024/3	2025年3月期 FY2025/3	2026年3月期 FY2026/3	2027年3月期中間期 FY2027/3 Interim
研究開発費　R&D expenses	9,042	10,354	12,037	6,769
設備投資　Capex	11,602	10,245	11,069	4,696
減価償却費（のれんの償却を除く） Depreciation（excl. Amortization of goodwill）	4,673	5,105	5,582	2,940

(百万円)(Million Yen)	2024年3月期 FY2024/3	2025年3月期 FY2025/3	2026年3月期 FY2026/3	2027年3月期 中間期 FY2027/3 Interim
営業活動によるキャッシュフロー Cash flows from operating activities	4,892	28,824	25,012	29,338
投資活動によるキャッシュフロー Cash flows from investing activities	-10,563	2,541	-11,491	-4,827
フリーキャッシュフロー Free cash flows	-5,671	31,365	13,520	24,511
財務活動によるキャッシュフロー Cash flows from financing activities	1,616	-13,991	-15,674	-8,797
現金及び現金同等物に係る換算差額等 Adjustments	755	404	689	432
現金及び現金同等物の期末残高 Cash and cash equivalents at the end of year	36,736	54,516	53,052	69,198

(従業員) (# of Employees)	2024年3月期 FY2024/3	2025年3月期 FY2025/3	2026年3月期 FY2026/3	2027年3月期中間期 FY2027/3 Interim
正社員合計　Total full-time employees	2,658	2,767	2,890	2,994
期間平均臨時従業員数 (外書) Average number of part-time employees, not included in the above figure	1,225	1,258	1,365	1,394
従業員合計 (※1)　Number of employees	3,883	4,025	4,255	4,388

※1: 従業員合計は、正社員合計人数と、期間平均臨時従業員数の単純合算です。"Number of employees" is a simple sum of the total number of regular employees and the average number of temporary employees during the period.